

## P/N: FASDRH1207-4R7N6R8

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## Reliability Testing:

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Ltem	Specified value	Test methods		
High temperature Storage test Reference documents: MIL-STD-202G Method 108A	1.No case deformation or change in appearance. 2.ΔL/L≤10%. 3.ΔQ/Q≤30%. 4.ΔDCR/DCR≤10%.	Temperature:85±2°C Time:96±2 hours. Tested not less than 1 hour, not more than 2 hours at room temperature.		
Low temperature Storage test. Referencedocuments: IEC 68-2-1A 6.1 6.2	1.No case deformation or change in appearance. 2.ΔL/L≤10%. 3.ΔQ/Q≤30%. 4.ΔDCR/DCR≤10%.	Temperature:25±2°C Time:96±2 hours. Tested not less than 1 hour, not more than 2 hours at room temperature. $\underbrace{\overset{\text{Room}}{\overset{\text{Temp}}{\overset{\text{Out}}{\overset{\text{Out}}{\overset{\text{Out}}{\overset{\text{Com}}{\overset{\text{Out}}}{\overset{\text{Out}}{\overset{\text{Out}}{\overset{\text{Out}}}{\overset{\text{Out}}{\overset{\text{Out}}}{\overset{\text{Out}}{\overset{\text{Out}}}{\overset{\text{Out}}}{\overset{\overset{\text{Out}}}{\overset{\text{Out}}}{\overset{\overset{\text{Out}}}{\overset{\text{Out}}}{\overset{\overset{\text{Out}}}{\overset{\overset{\text{Out}}}{\overset{\overset{\text{Out}}}{\overset{\overset{\text{Out}}}{\overset{\overset{\text{Out}}}{\overset{\overset{\text{Out}}}{\overset{\overset{\text{Out}}}{\overset{\overset{\text{Out}}}{\overset{\overset{\text{Out}}}{\overset{\overset{\text{Out}}}{\overset{\overset{\text{Out}}}{\overset{\overset{\text{Out}}}{\overset{\overset{\text{Out}}}}{\overset{\overset{\overset{\text{Out}}}{\overset{\overset{\text{Out}}}}{\overset{\overset{\overset{\text{Out}}}}{\overset{\overset{\overset{\text{Out}}}}{\overset{\overset{\overset{\text{Out}}}}{\overset{\overset{\overset{\text{Out}}}}{\overset{\overset{\overset{\overset{\text{Out}}}}}{\overset{\overset{\overset{\overset{\overset{\text{Out}}}}}{\overset{\overset{\overset{\overset{\overset{\text{Out}}}}}}{\overset{\overset{\overset{\overset{\overset{\overset{\overset{\overset{}}}}}{\overset{\overset{\overset$		
Humidity test Reference Documents: MIL-STD-202G Method 103B	1.No case deformation or change in appearance. 2.ΔL/L≤10%. 3.ΔQ/Q≤30%. 4.ΔDCR/DCR≤10%.	1.Dry oven at a temperature of 40°±5°C for 24 hours. 2.Measurements At the end of this period 3.Exposure:Temperature:40±2°C,Humidity: 93±3%RH Time:96±2 hours. 4.Tested while the specimens are still in the chamber. 5.Tested not less than 1 hour, nor more than 2 hours at room temperature.		
Heat endurance of Reflow soldering	1.No case deformation or change in appearance. 2.ΔL/L≤10%. 3.ΔQ/Q≤30%. 4.ΔDCR/DCR≤10%.	Preheat:150°C,60 second. Solder:Sn/Ag/Cu. Solder:Temperature:260±5°C. Flux:Rosin flux. Reflow peak time 10 second at 260°C		

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Ltem	Specified value	Test methods			
Thermal shock test Reference documents: MIL-STD-202G Method 107G	1.No case deformation or change in appearance.         2.ΔL/L≤10%.         3.ΔQ/Q≤30%.         4.ΔDCR/DCR≤10%.         For T:weighe≤28g:15 Min 28g≤weight≤136g:30 Min	First-40°C for T time,next+125°C Ttime as 1 cycle. Go through 20 cycles.			
Solderability test Reference documents: MIL-STD-202G Method 208H IPC J-STD-002B	Terminals area must have 95% Min. Solder coverage.	Dip pads in flux then dip in solder pot at 245±5°C for 5 second. Soler:Sn(93.5)Ag(3.5). Flux:Rosin flux.			
Vibration test Reference documents: MIL-STD-202G Method 201A	1.No case deformation or change in appearance. 2.ΔL/L≤10%. 3.ΔQ/Q≤30%. 4.ΔDCR/DCR≤10%.	Apply frequency 10~55Hz. 0.75mm amplitude in each of perpendicular direction for 2 hours.(total 6 hours).			
Drop test Reference documents: MIL-STD-202G Method 203G	1.No case deformation or change in appearance.         2.ΔL/L≤10%.         3.ΔQ/Q≤30%.         4.ΔDCR/DCR≤10%.         For T:weighe≤28g:15 Min 28g≤weight≤136g:30 Min	Packaged & Drop down from 1m with 981m/s2(100G)attitude in 1 angle 1 ridges & 2 surfaces orientations.			
Terminal strength push test Reference documents: JIS C 5321:1997	Pulling test: DEFINE:A:sectional area of terminal A≤8(Sq M) Force≥5N time:30sec 8(Sq M) <a≤20(sq m)<br="">Force≥10N time:10sec 20(Sq M)<a force≥20n<br="">time:10sec Bending test: Soldering the products on PCB,after the pulling testand bending test, terminal should not pull off</a></a≤20(sq>	Bend the testing PCB at middle point, the deflection shall be 2mm $Pulling test$ $R_{0.5}$ $R_{$			

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					¥	Checked: Beson. zhan		Document/Rev: 00
					Tolerances unless otherwise specified:	Checked: Beson. Zhan		Specification Sheet: 3 of 4
REV	DESCRIPTION	APPD	DATE		(.X)±0.50 (.XX)±0.25 Unit of measurement: mm	Approved: Anson. zhan		Date of Recognition: July./14/2020

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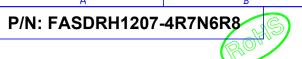
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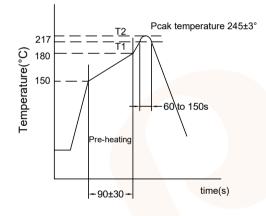
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Ltem	Specified value	Test methods
Resistance to solvent test Reference documents: IEC 68-2-45:1993	No case deformation or change in appearance,or obliteration of marking	To dip parts into IPA solvent for 5±0.5Min, then drying them atroom temp for 5 Min,at last,to brushing making 10 times.
Electronic characteristic test of major products	Refer to catalogue of specific products	Refer to catalogue of specific products
Overload test Reference documents:	1.During the test no smoke,no peculiar,smell, no fire	Apply twice as rated current for 5 minutes.

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Recommended solderability temperature profile:



Use rosin-based flux

Don't use high acidic flux with halide content exceeding 0.2(wt)% (chlorine conversion value). Use lead-free solder, use Sn-3.0Ag-0.5Cu solder Standard thickness of solder paste:0.12-0.15mm

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RE	/ DESCRIPTION	APPD	DATE		Unit of measurement: mm	Approved: Anson. zhan	Material Number: A341207HS020	Date of Recognition: July./14/2020	1